

Title (en)
METHOD FOR BONDING CLOCK COMPONENTS

Title (de)
KLEBEVERFAHREN FÜR UHRENKOMPONENTEN

Title (fr)
PROCÉDÉ DE COLLAGE DE COMPOSANTS HORLOGERS

Publication
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Application
EP 19194407 A 20190829

Priority
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Abstract (en)
[origin: WO2021037408A1] The invention relates to a method for bonding clock components, comprising the application of an adhesive to a first and/or second clock component to be bonded to each other, and depositing a priming coat onto at least one of the first and second components to be bonded by spraying a primer composition into a localised bonding area, followed by the solidification of the primer composition. The priming coat is deposited prior to the application of the adhesive if the adhesive is applied to the same component(s) as the priming coat.

Abstract (fr)
L'invention concerne un procédé de collage de composants horlogers, comprenant l'application d'une colle sur un premier et/ou un second composant horloger à coller l'un sur l'autre et la formation d'une couche d'accrochage sur au moins un des premier et second composants à coller par projection d'une composition de primaire dans une zone de liaison localisée suivie de la solidification de la composition de primaire. La formation de la couche d'accrochage est effectuée avant l'application de la colle si la colle est appliquée sur le(s) même(s) composant(s) que la couche d'accrochage et.

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Citation (applicant)
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